Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**.012”**

**CATHODE**

**.014”**

**CATHODE**

**Top Material: Al**

**Backside Material: Si**

**Bond Pad Size: .0035 x .0035”**

**Backside Potential: Connect to ANODE**

**APPROVED BY: DK DIE SIZE .012” X .014” DATE: 12/15/22**

**MFG: SILICON SUPPLIES THICKNESS .009” P/N: TPD5030**

**DG 10.1.2**

#### Rev B, 7/1